

50864 ✓ ACTIVE

TE Internal #: 50864

Pin Sockets, Socket Length 6.53 mm [.257 in], PCB Hole Diameter .

062 in [1.57 mm], Closed Bottom, .326 – .518 mm<sup>2</sup> Wire Size, 22 – 20

AWG Wire Size

[View on TE.com >](#)



Connectors > Socket Connectors > Pin Sockets > Miniature Spring Sockets: Closed Bottom, Beryllium Copper, 5A



Socket Length: 6.53 mm [.257 in]

PCB Hole Diameter: 1.57 mm [.062 in]

Socket Sleeve Style: **Closed Bottom**

Wire Size: .326 – .518 mm<sup>2</sup>

[All Miniature Spring Sockets: Closed Bottom, Beryllium Copper, 5A \(11\)](#)

## Features

### Product Type Features

Socket Sleeve Style	Closed Bottom
Connector System	Cable-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board

### Configuration Features

Compatible With Wire & Cable Type	Discrete Wire
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### Body Features

Sleeve Material	Copper
Sleeve Plating Material	Gold Flash over Nickel

### Contact Features

Contact Spring Plating Material	Gold
Contact Spring Plating Thickness	.762 μm[30 μin]
Contact Mating Area Plating Material Thickness	30 μm[30 μin]
Contact Base Material	Beryllium Copper



Contact Current Rating (Max)	5 A
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### Termination Features

Insertion Method	Hand/Semi-Automatic/Automatic
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Termination Method to Printed Circuit Board	Through Hole - Press-Fit
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Termination Method to Wire & Cable	Solder
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### Dimensions

PCB Thickness (Recommended)	.79 – 3.18 mm [.031 – .125 in]
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Socket Length	6.53 mm [.257 in]
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PCB Hole Diameter	1.57 mm [.062 in]
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Wire Size	.326 – .518 mm <sup>2</sup>
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Mating Pin Diameter Range	.66 – .84 mm [.026 – .033 in]
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### Usage Conditions

Operating Temperature Range	-65 – 125 °C [-85 – 257 °F]
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### Operation/Application

Solder Process Feature	None
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Circuit Application	Power & Signal
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### Packaging Features

Packaging Quantity	2000
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Packaging Method	Bag, Loose Piece
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### Other

Spring Material	Beryllium Copper
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### Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
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EU ELV Directive 2000/53/EC	Compliant
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China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
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EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JUNE 2022 (224) Does not contain REACH SVHC
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Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC
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Free

Solder Process Capability

Pin-in-Paste capable to 260°C

## Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

## Compatible Parts



TE Part # 50864-1  
SOCKET,MIN-SPR SN-AU SER-3

## Documents

## Product Drawings

SOCKET,MIN-SPR AU SER-3

English

## CAD Files

Customer View Model

ENG\_CVM\_CVM\_50864\_T.2d\_dxf.zip

English

## 3D PDF

3D

Customer View Model

ENG\_CVM\_CVM\_50864\_T.3d\_igs.zip

English

Customer View Model

ENG\_CVM\_CVM\_50864\_T.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

## Product Specifications



### Application Specification

English

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### Product Environmental Compliance

#### Product Compliance

English

#### Product Compliance

English